

TL7757 SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

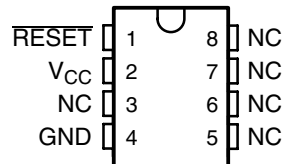
SLVS041I – SEPTEMBER 1991 – REVISED AUGUST 2003

- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Low Standby Current . . . 20 μ A
- RESET Output Defined When V_{CC} Exceeds 1 V
- Precision Threshold Voltage
4.55 V $\pm$ 120 mV
- High Output Sink Capability . . . 20 mA
- Comparator Hysteresis Prevents Erratic Resets

description/ordering information

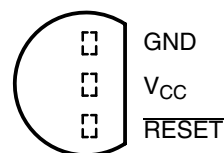
The TL7757 is a supply-voltage supervisor designed for use in microcomputer and microprocessor systems. The supervisor monitors the supply voltage for undervoltage conditions. During power up, when the supply voltage, V_{CC} , attains a value approaching 1 V, the RESET output becomes active (low) to prevent undefined operation. If the supply voltage drops below threshold voltage level (V_{IT-}), the RESET output goes to the active (low) level until the supply undervoltage fault condition is eliminated.

**D PACKAGE
(TOP VIEW)**

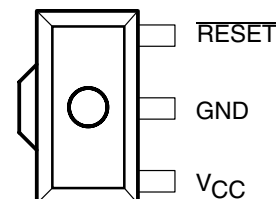


NC—No internal connection

**LP PACKAGE
(TOP VIEW)**



**PK PACKAGE
(TOP VIEW)**



GND is in electrical contact with the tab.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (D)	Tube of 75	TL7757CD	7757C
		Reel of 2500	TL7757CDR	
	SOT (PK)	Reel of 1000	TL7757CPK	T7
	TO226 / TO-92 (LP)	Bulk of 1000	TL7757CLP	TL7757C
		Reel of 2000	TL7757CLPR	
–40°C to 85°C	SOIC (D)	Tube of 75	TL7757ID	7757I
		Reel of 2500	TL7757IDR	
	SOT (PK)	Reel of 1000	TL7757IPK	7I
	TO226 / TO-92 (LP)	Bulk of 1000	TL7757ILP	TL7757I
		Reel of 2000	TL7757ILPR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

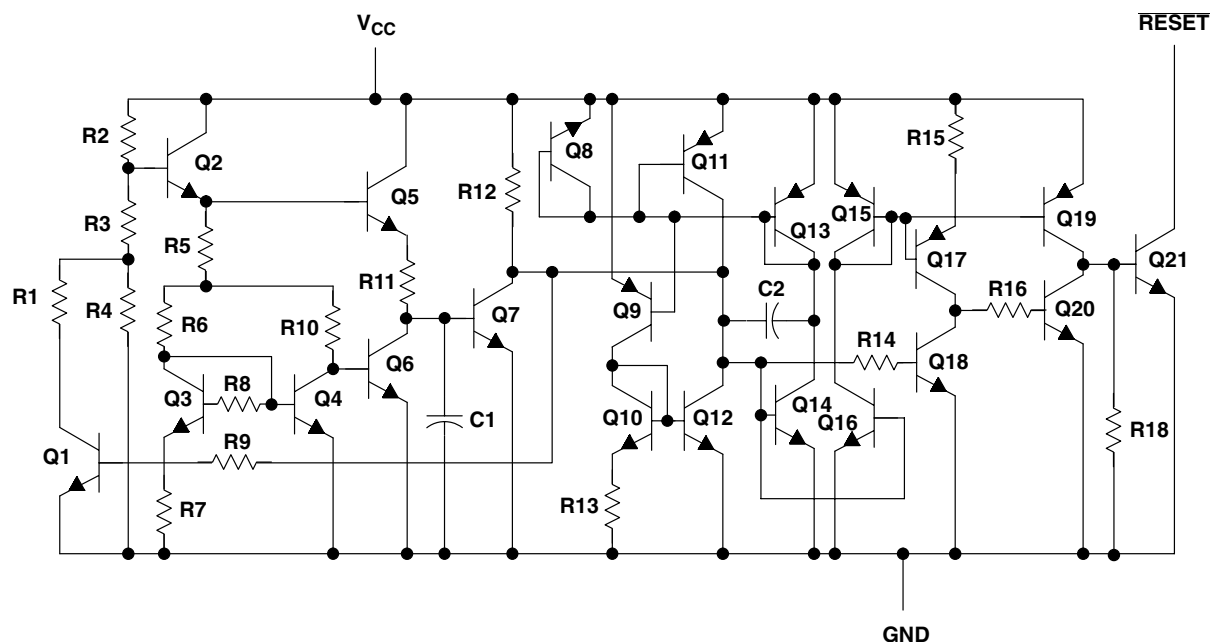
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TL7757 SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

SLVS0411 – SEPTEMBER 1991 – REVISED AUGUST 2003

equivalent schematic



ACTUAL DEVICE COMPONENT COUNT	
Transistors	27
Resistors	20
Capacitors	2

absolute maximum ratings over operating junction temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 20 V
Off-state output voltage range (see Note 1)	–0.3 V to 20 V
Output current, I_O	30 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	
D package	97°C/W
LP package	140°C/W
PK package	52°C/W
Operating virtual junction temperature, T_J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network terminal ground.

2. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage	1	7	V
V_{OH}	High-level output voltage		15	V
I_{OL}	Low-level output current		20	mA
T_A	Operating free-air temperature	TL7757C	0	70
		TL7757I	–40	85
				°C

electrical characteristics at specified free-air temperature

PARAMETER	TEST CONDITIONS	T_A	TL7757C			UNIT
			MIN	TYP	MAX	
V_{IT-}	Negative-going input threshold voltage at V_{CC}	25°C	4.43	4.55	4.67	V
		0°C to 70°C	4.4		4.7	
$V_{hys}^{\dagger}$	Hysteresis at V_{CC}	25°C	40	50	60	mV
		0°C to 70°C	30		70	
V_{OL}	Low-level output voltage $I_{OL} = 20\text{ mA}, V_{CC} = 4.3\text{ V}$	25°C		0.4	0.8	V
		0°C to 70°C			0.8	
I_{OH}	High-level output current $V_{CC} = 7\text{ V}, V_{OH} = 15\text{ V},$ See Figure 1	25°C			1	μA
		0°C to 70°C			1	
$V_{res}^{\ddagger}$	Power-up reset voltage $R_L = 2.2\text{ k}\Omega,$ V_{CC} slew rate $\leq 5\text{ V}/\mu\text{s}$	25°C		0.8	1	V
		0°C to 70°C			1.2	
I_{CC}	Supply current $V_{CC} = 4.3\text{ V}$	25°C		1400	2000	μA
		0°C to 70°C			2000	
		$V_{CC} = 5.5\text{ V}$			40	

† This is the difference between positive-going input threshold voltage, V_{IT+} , and negative-going input threshold voltage, V_{IT-} .

‡ This is the lowest voltage at which RESET becomes active.

switching characteristics at specified free-air temperature

PARAMETER	TEST CONDITIONS	T_A	TL7757C			UNIT
			MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low-to-high-level output V_{CC} slew rate $\leq 5\text{ V}/\mu\text{s},$ See Figures 2 and 3	25°C		3.4	5	μs
		0°C to 70°C			5	
t_{PHL}	Propagation delay time, high-to-low-level output See Figures 2 and 3	25°C		2	5	μs
		0°C to 70°C			5	
t_r	Rise time V_{CC} slew rate $\leq 5\text{ V}/\mu\text{s},$ See Figures 2 and 3	25°C		0.4	1	μs
		0°C to 70°C			1	
t_f	Fall time See Figures 2 and 3	25°C		0.05	1	μs
		0°C to 70°C			1	
$t_{w(min)}$	Minimum pulse duration at V_{CC} for output response	25°C			5	μs
		0°C to 70°C			5	

TL7757

SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

SLVS041I – SEPTEMBER 1991 – REVISED AUGUST 2003

electrical characteristics at specified free-air temperature

PARAMETER	TEST CONDITIONS	T _A	TL7757I			UNIT
			MIN	TYP	MAX	
V _{IT-} Negative-going input threshold voltage at V _{CC}		25°C	4.43	4.55	4.67	V
		-40°C to 85°C	4.4		4.7	
V _{hys} [†] Hysteresis at V _{CC}		25°C	40	50	60	mV
		-40°C to 85°C	30		70	
V _{OL} Low-level output voltage	I _{OL} = 20 mA, V _{CC} = 4.3 V	25°C		0.4	0.8	V
		-40°C to 85°C			0.8	
I _{OH} High-level output current	V _{CC} = 7 V, V _{OH} = 15 V, See Figure 1	25°C			1	μA
		-40°C to 85°C			1	
V _{res} [‡] Power-up reset voltage	R _L = 2.2 kΩ, V _{CC} slew rate ≤ 5 V/μs	25°C		0.8	1	V
		-40°C to 85°C			1.2	
I _{CC} Supply current	V _{CC} = 4.3 V	25°C		1400	2000	μA
		-40°C to 85°C			2100	
	V _{CC} = 5.5 V	-40°C to 85°C			40	

[†] This is the difference between positive-going input threshold voltage, V_{IT+}, and negative-going input threshold voltage, V_{IT-}.

[‡] This is the lowest voltage at which RESET becomes active.

switching characteristics at specified free-air temperature

PARAMETER	TEST CONDITIONS	T _A	TL7757I			UNIT
			MIN	TYP	MAX	
t _{pLH} Propagation delay time, low-to-high-level output	V _{CC} slew rate ≤ 5 V/μs, See Figures 2 and 3	25°C		3.4	5	μs
		-40°C to 85°C			5	
t _{pHL} Propagation delay time, high-to-low-level output	See Figures 2 and 3	25°C		2	5	μs
		-40°C to 85°C			5	
t _r Rise time	V _{CC} slew rate ≤ 5 V/μs, See Figures 2 and 3	25°C		0.4	1	μs
		-40°C to 85°C			1	
t _f Fall time	See Figures 2 and 3	25°C		0.05	1	μs
		-40°C to 85°C			1	
t _{w(min)} Minimum pulse duration at V _{CC} for output response		25°C			5	μs
		-40°C to 85°C			5	



PARAMETER MEASUREMENT INFORMATION

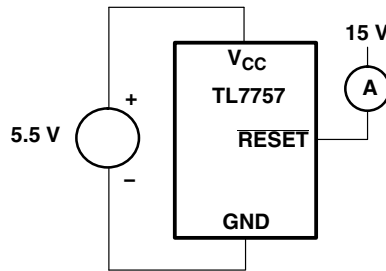
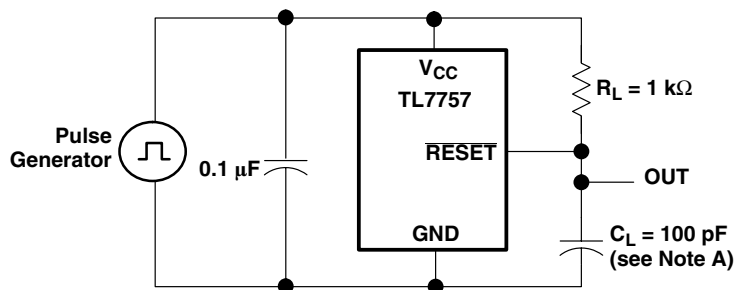
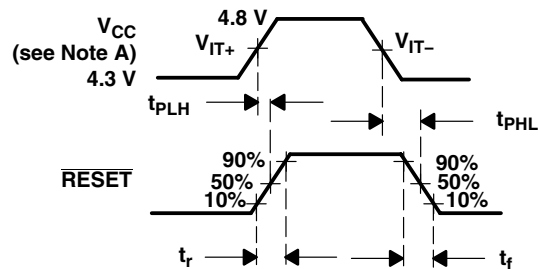


Figure 1. Test Circuit for Output Leakage Current



NOTE A: Includes jig and probe capacitance

Figure 2. Test Circuit for $\overline{\text{RESET}}$ Output Switching Characteristics



NOTE A: V_{CC} slew rate $\leq 5 \mu\text{s}$

Figure 3. Switching Diagram

TL7757

SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

SLVS0411 – SEPTEMBER 1991 – REVISED AUGUST 2003

TYPICAL CHARACTERISTICS†

Table of Graphs

	FIGURE
V_{CC} Supply voltage vs $\overline{\text{RESET}}$ output voltage	4
I_{CC} Supply current vs Supply voltage	5
I_{CC} Supply current vs Free-air temperature	6
V_{OL} Low-level output voltage vs Low-level output current	7
V_{OL} Low-level output voltage vs Free-air temperature	8
I_{OL} Output current vs Supply voltage	9
V_{IT-} Input threshold voltage (negative-going V_{CC}) vs Free-air temperature	10
V_{res} Power-up reset voltage vs Free-air temperature	11
V_{res} Power-up reset voltage and supply voltage vs Time	12
Propagation delay time	13

SUPPLY VOLTAGE
vs
RESET OUTPUT VOLTAGE

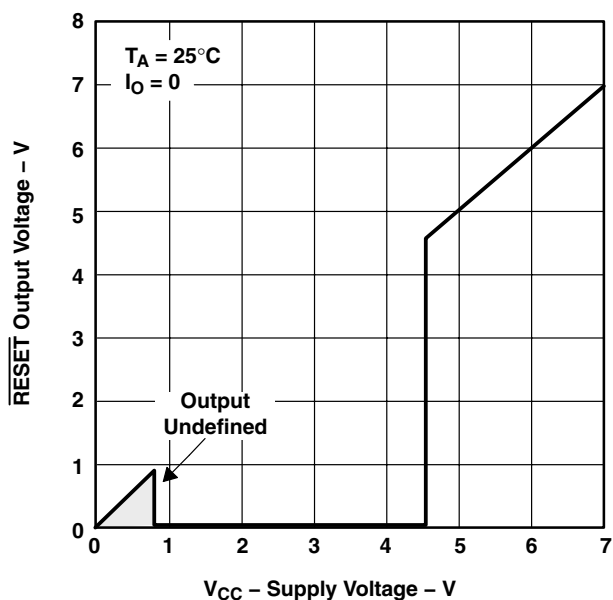


Figure 4

SUPPLY CURRENT
vs
SUPPLY VOLTAGE

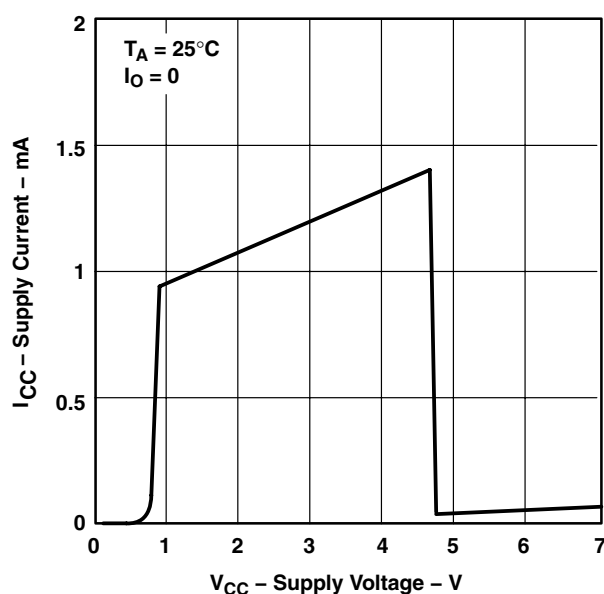
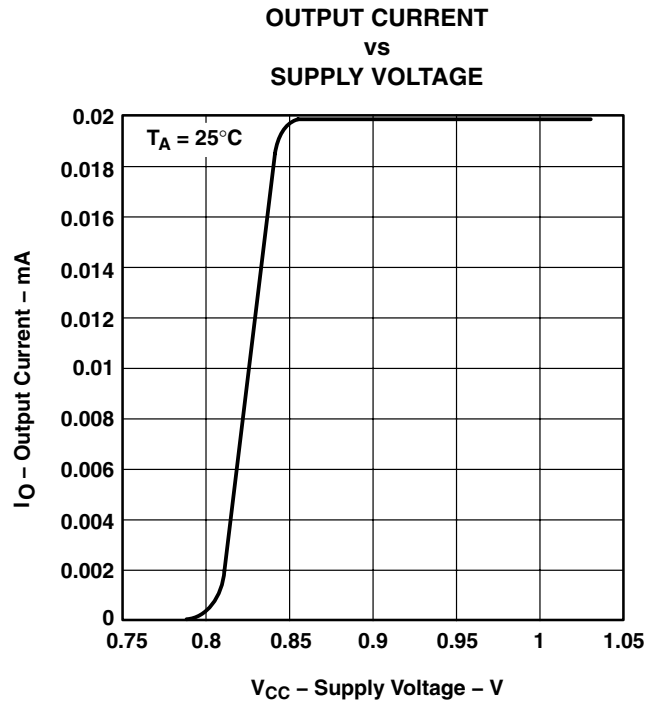
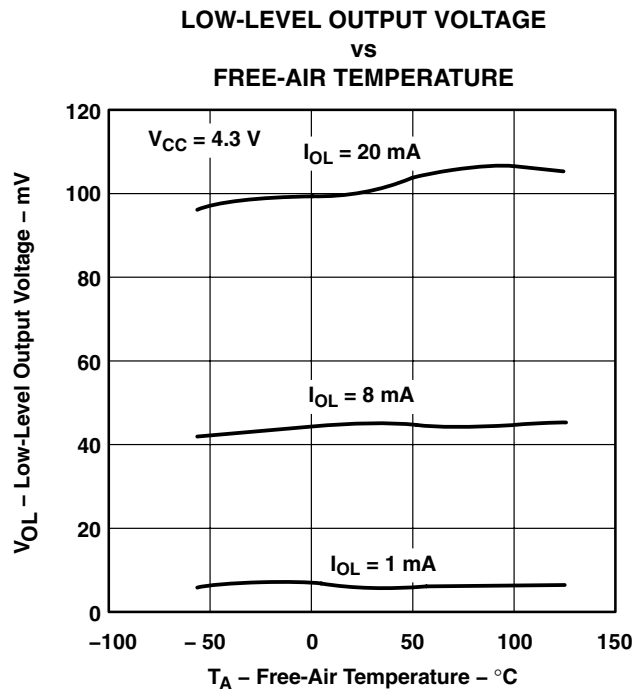
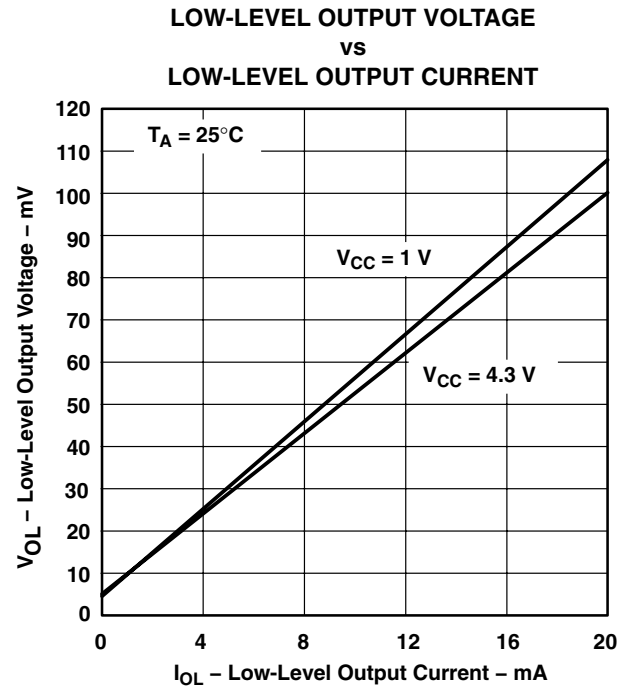
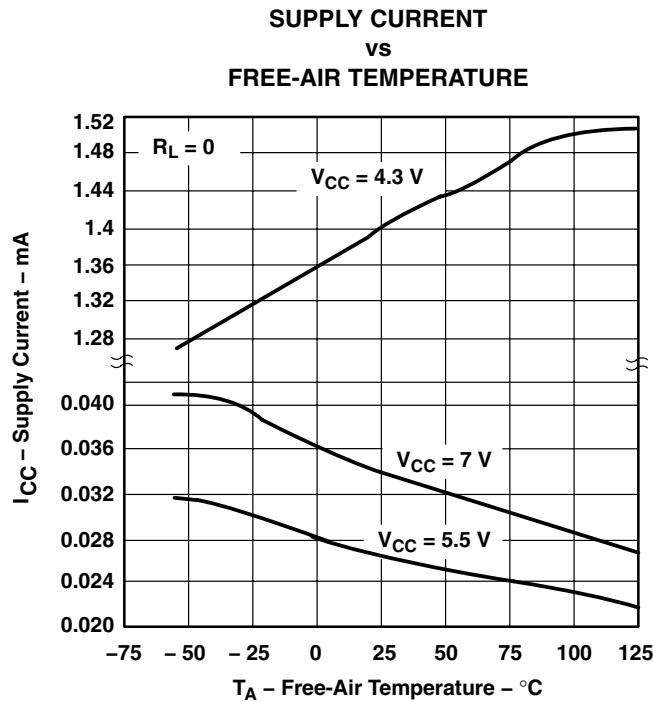


Figure 5

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TL7757 SUPPLY-VOLTAGE SUPERVISOR AND PRECISION VOLTAGE DETECTOR

SLVS041I – SEPTEMBER 1991 – REVISED AUGUST 2003

TYPICAL CHARACTERISTICS†

INPUT THRESHOLD VOLTAGE
(NEGATIVE-GOING V_{CC})
vs
FREE-AIR TEMPERATURE

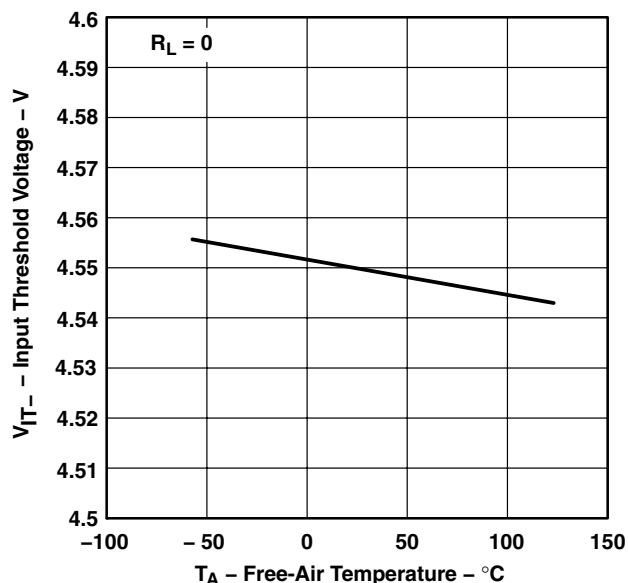


Figure 10

POWER-UP RESET VOLTAGE
vs
FREE-AIR TEMPERATURE

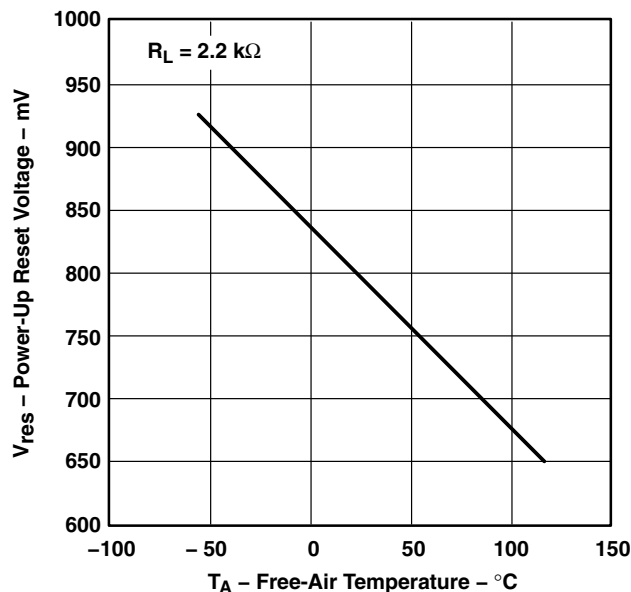


Figure 11

POWER-UP RESET VOLTAGE
AND SUPPLY VOLTAGE
vs
TIME

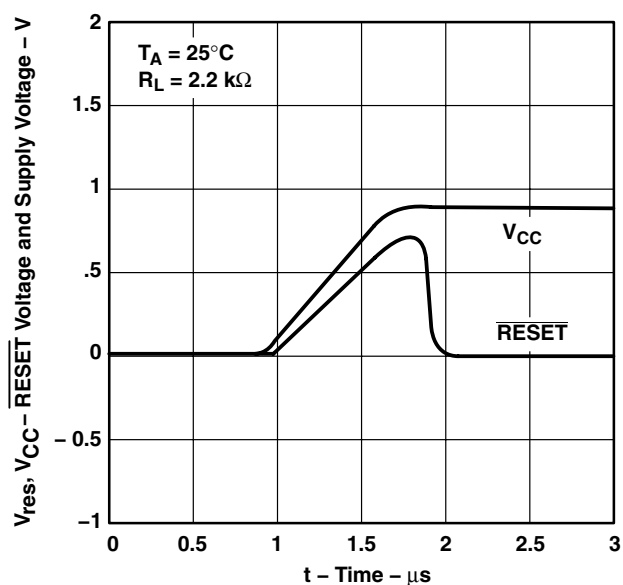


Figure 12

PROPAGATION DELAY TIME

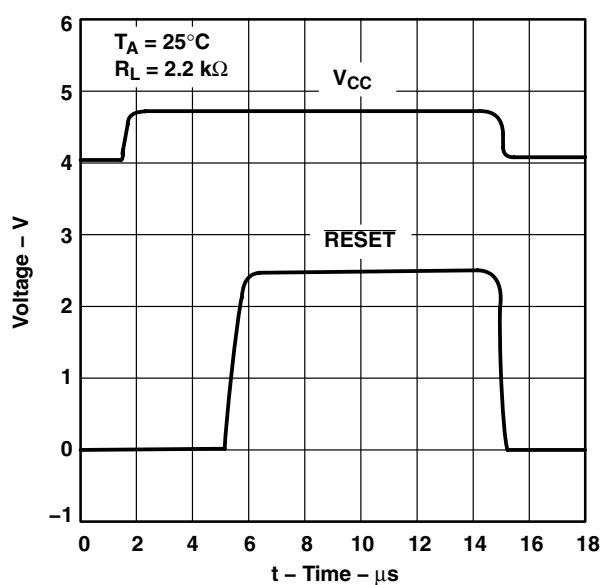
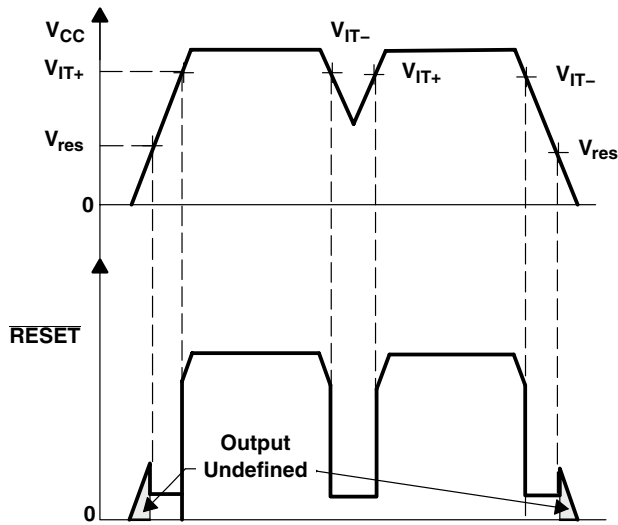


Figure 13

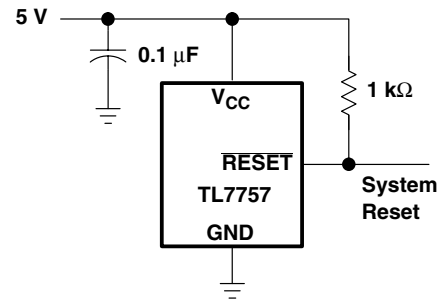
† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION

TYPICAL TIMING DIAGRAM



TYPICAL APPLICATION DIAGRAM



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL7757CD	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C
TL7757CD.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C
TL7757CDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C
TL7757CDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	7757C
TL7757CLP	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	TL7757C
TL7757CLP.A	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	0 to 70	TL7757C
TL7757CLPR	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	TL7757C
TL7757CLPR.A	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	TL7757C
TL7757CPK	Active	Production	SOT-89 (PK) 3	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	0 to 70	T 7
TL7757CPK.A	Active	Production	SOT-89 (PK) 3	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	0 to 70	T 7
TL7757ID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	7757I
TL7757ID.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	7757I
TL7757IDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	7757I
TL7757IDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	7757I
TL7757ILP	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	-40 to 85	TL7757I
TL7757ILP.A	Active	Production	TO-92 (LP) 3	1000 BULK	Yes	SN	N/A for Pkg Type	-40 to 85	TL7757I
TL7757ILPR	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	-40 to 85	TL7757I
TL7757ILPR.A	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	-40 to 85	TL7757I
TL7757IPK	Active	Production	SOT-89 (PK) 3	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 85	7I
TL7757IPK.A	Active	Production	SOT-89 (PK) 3	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 85	7I

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL7757CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7757CPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3
TL7757IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL7757IPK	SOT-89	PK	3	1000	180.0	12.4	4.91	4.52	1.9	8.0	12.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL7757CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL7757CPK	SOT-89	PK	3	1000	340.0	340.0	38.0
TL7757IDR	SOIC	D	8	2500	353.0	353.0	32.0
TL7757IPK	SOT-89	PK	3	1000	340.0	340.0	38.0

TUBE

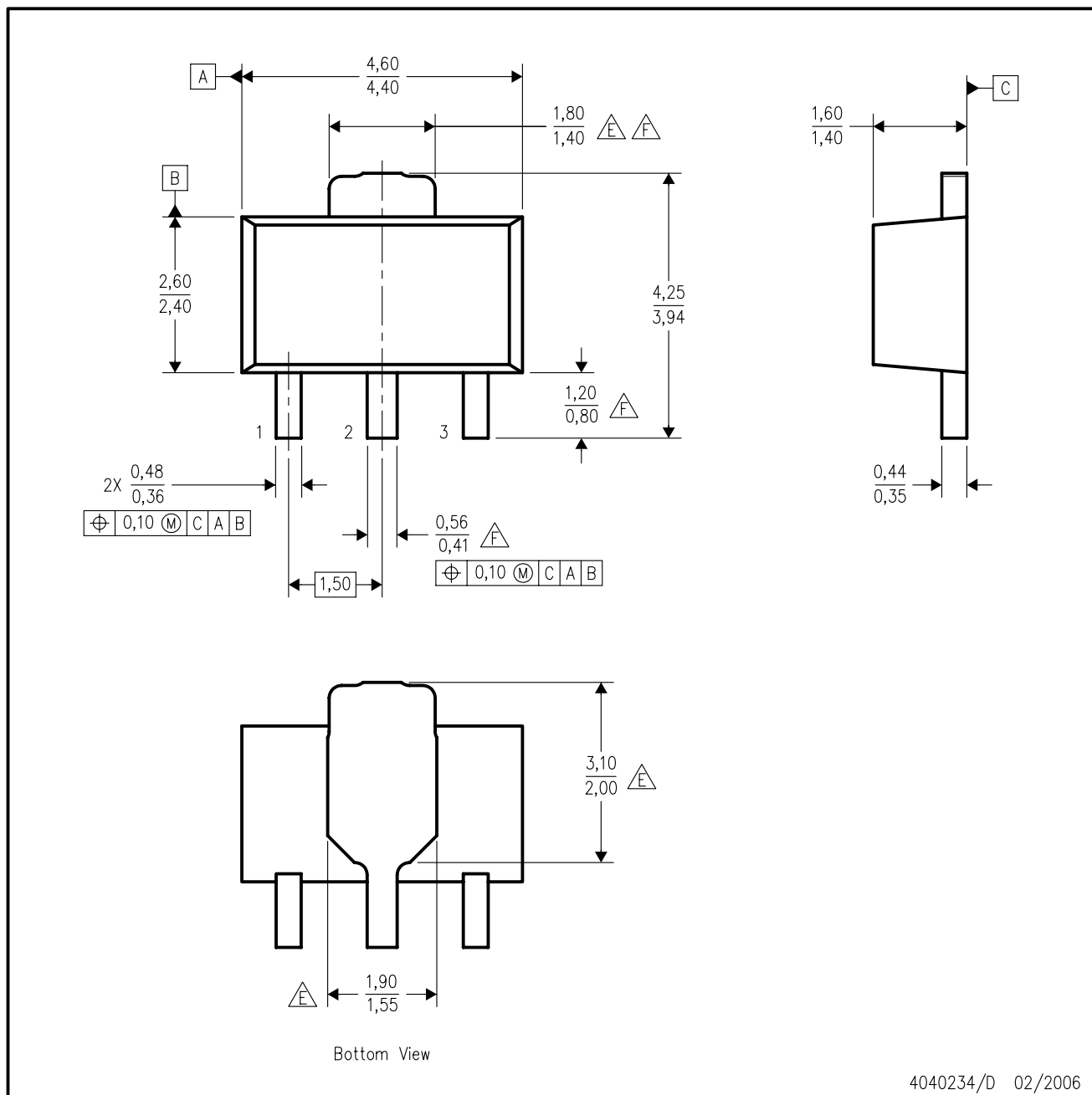


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TL7757CD	D	SOIC	8	75	507	8	3940	4.32
TL7757CD.A	D	SOIC	8	75	507	8	3940	4.32
TL7757ID	D	SOIC	8	75	507	8	3940	4.32
TL7757ID.A	D	SOIC	8	75	507	8	3940	4.32

PK (R-PSSO-F3)

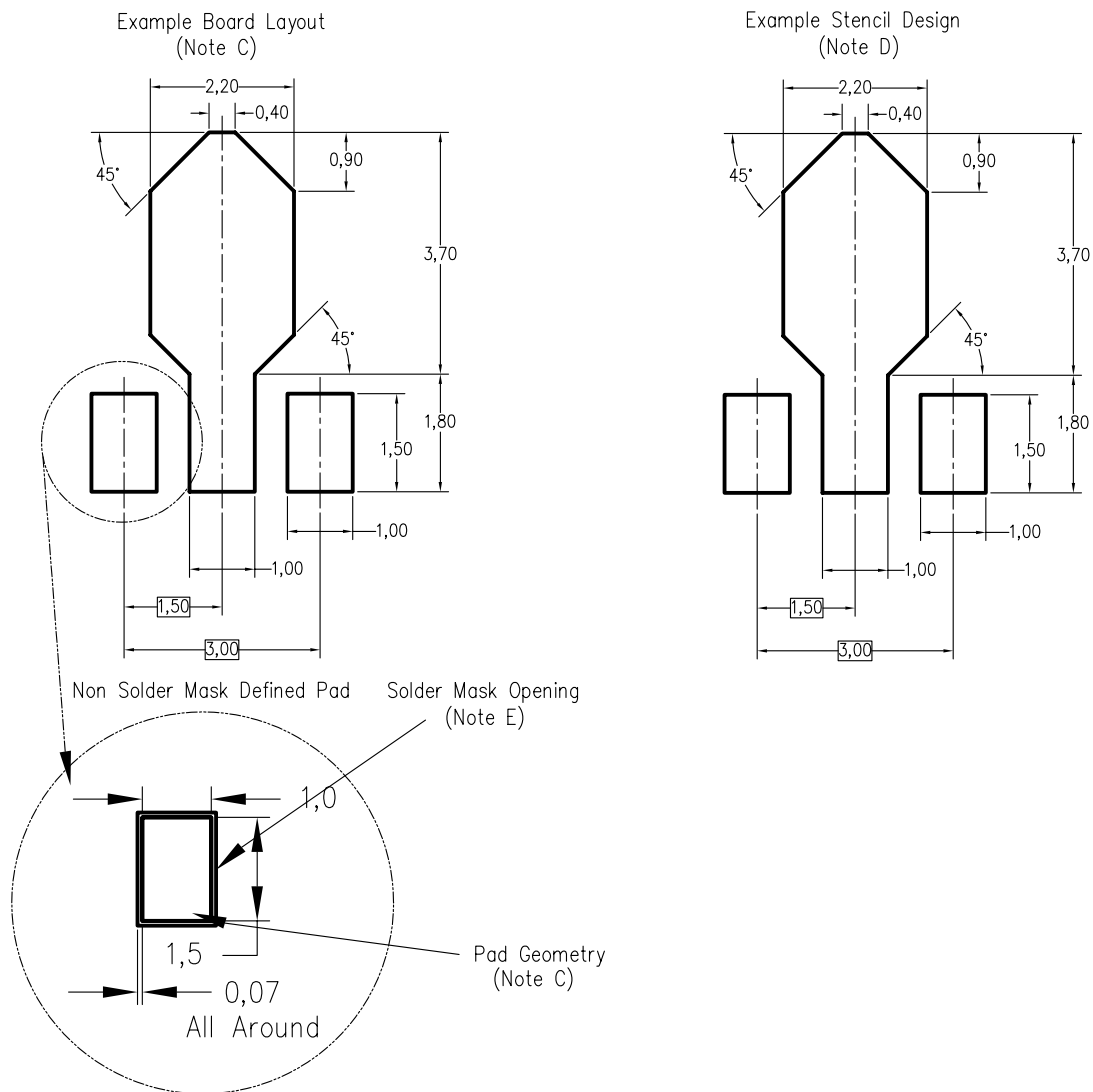
PLASTIC SINGLE-IN-LINE PACKAGE



4040234/D 02/2006

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - The center lead is in electrical contact with the tab.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion not to exceed 0.15 per side.
- △E Thermal pad contour optional within these dimensions.
- △F Falls within JEDEC TO-243 variation AA, except minimum lead length, pin 2 minimum lead width, minimum tab width.

PK (R-PDSO-G3)



4208221/A 09/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

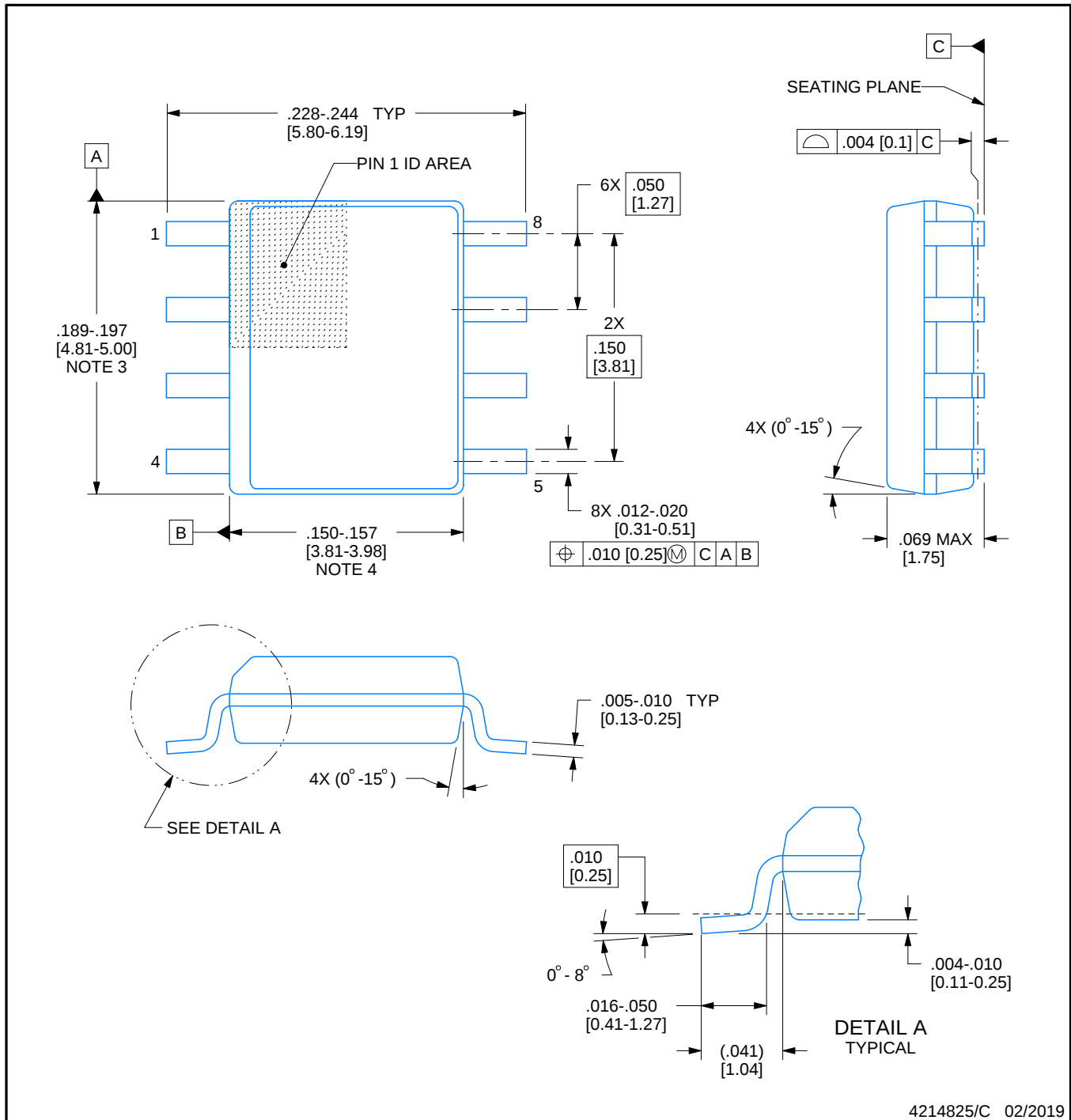


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

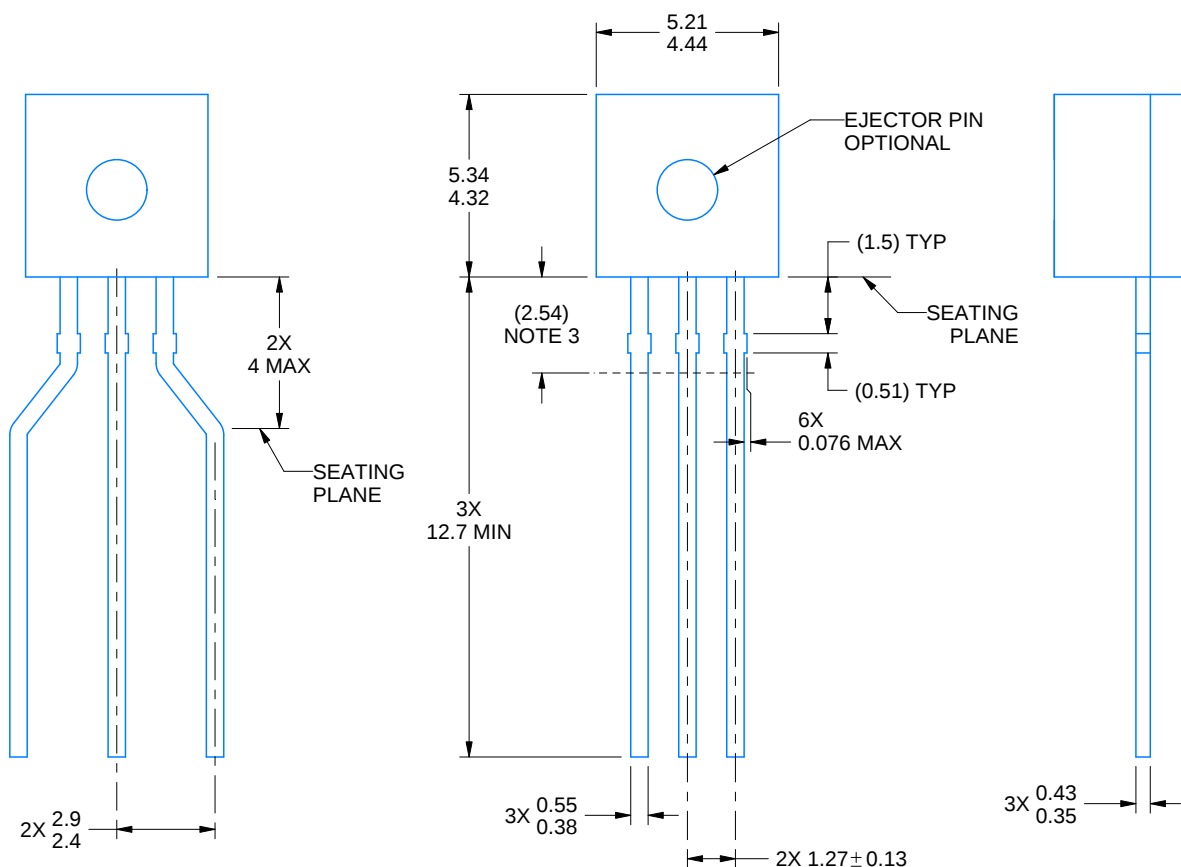
LP0003A



PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



4215214/C 04/2025

NOTES:

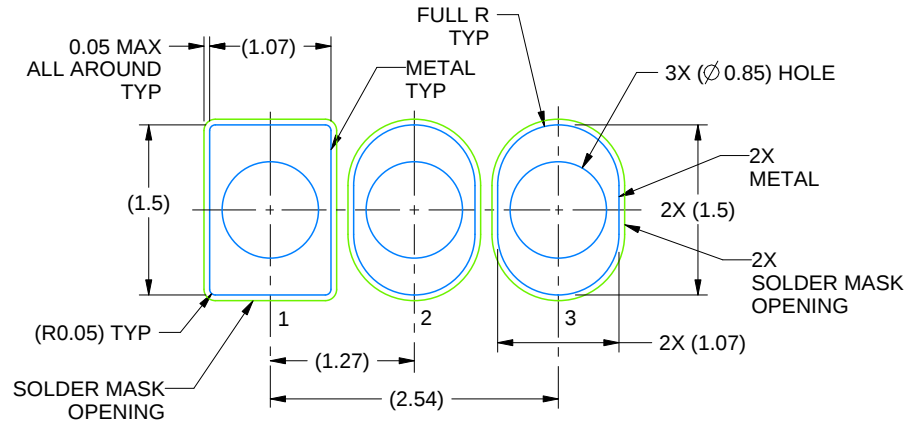
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.

EXAMPLE BOARD LAYOUT

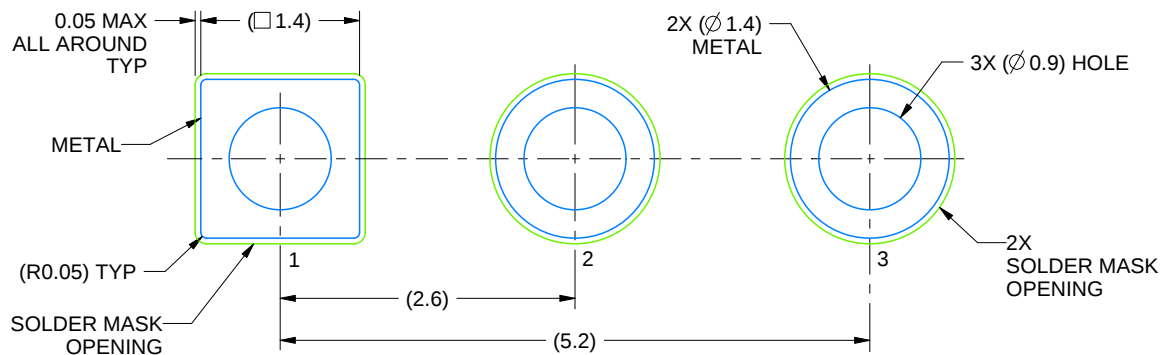
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

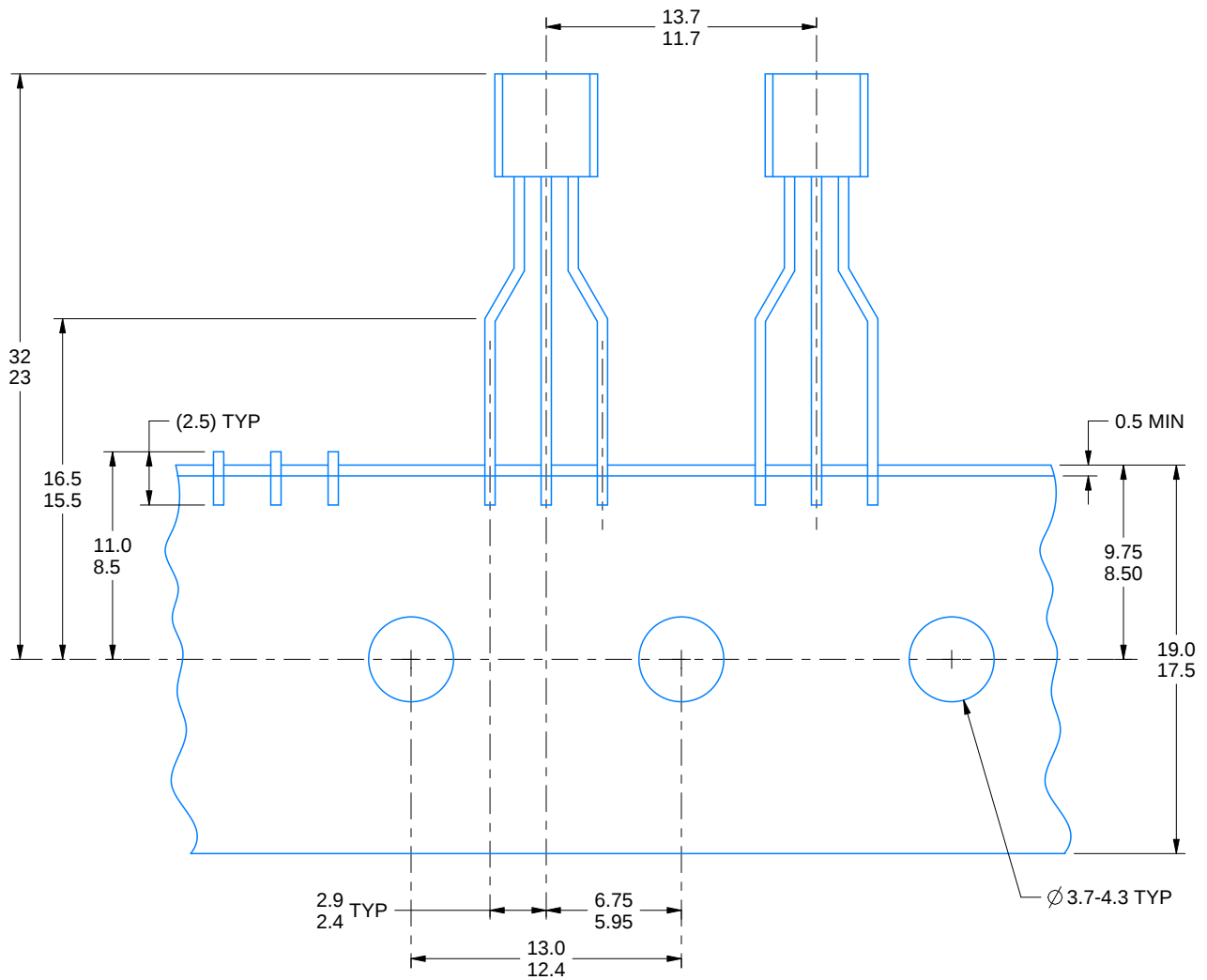
4215214/C 04/2025

TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/C 04/2025

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